503934427 07/27/2016

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YOSHIKI MATOBA	07/05/2016
AKIHIRO TAKEDA	07/05/2016
SHINGO TSUBOI	07/05/2016
TOSHIHIRO SAKAI	07/05/2016

RECEIVING PARTY DATA

Name:	HITACHI HIGH-TECH SCIENCE CORPORATION	
Street Address:	24-14, NISHI-SHIMBASHI 1-CHOME, MINATO-KU	
City:	TOKYO	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15220880

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 12109.1040US01

NAME OF SUBMITTER: CURTIS B. HAMRE

SIGNATURE: /Curtis B. Hamre/

DATE SIGNED: 07/27/2016

Total Attachments: 2

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PATENT 503934427 REEL: 039273 FRAME: 0671

Docket No.

ASSIGNMENT OF PATENT APPLICATION

WHEREAS,

MATOBA, Yoshiki residing at c/o HITACHI HIGH-TECH SCIENCE CORPORATION, 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan

TAKEDA, Akihiro residing at c/o HITACHI HIGH-TECH SCIENCE CORPORATION, 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan

TSUBOI, Shingo residing at c/o HITACHI HIGH-TECH SCIENCE CORPORATION, 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan

SAKAI, Toshihiro residing at c/o HITACHI HIGH-TECH SCIENCE CORPORATION, 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan

(hereinafter called "THE UNDERSIGNED") have made an invention and have executed an application for Letters Patent of the United States for this invention which was filed on , entitled

X-RAY TRANSMISSION INSPECTION APPARATUS AND INSPECTION METHOD USING THE SAME

and which has been given application serial number

and

WHEREAS, HITACHI HIGH-TECH SCIENCE CORPORATION, which is organized under the laws of Japan and having an office and place of business at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan (hereinafter referred to as Assignee), wishes to acquire the entire right, title and interest in and to said invention and patent application and any Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, THE UNDERSIGNED hereby sell, assign, and transfer to the ASSIGNEE, its successors, legal representative and assigns, the entire right, title and interest for the United States in and to the invention disclosed in said application, and in and to said application, as well as to all divisions, continuations, or renewals thereof, all Letters Patent which may be granted therefrom, and all reissues or extensions of such patents, and THE UNDERSIGNED hereby authorize and request the Commissioner of Patents of the United States to issue all Letters Patent for said invention to the

PATENT REEL: 039273 FRAME: 0672 ASSIGNEE of the entire right, title and interest in and to the same, in accordance with the terms of this instrument.

THE UNDERSIGNED hereby agree that THE UNDERSIGNED, their executors and legal representatives will make, execute and deliver (without charge but at the expense of the ASSIGNEE) any and all other instruments in writing including any and all further application papers, affidavits, assignments and other documents, and will communicate to said ASSIGNEE, its successors and representatives all facts known to the UNDERSIGNED relating to said invention and the history thereof and will testify in all legal proceedings and generally do all things which may be necessary or desirable to vest the ASSIGNEE, it successors or assigns, the entire right, title and interest in and to the said invention, patent applications, Letters Patent, rights, titles, benefits, privileges, and advantages hereby sold, assigned and conveyed, or intended so to be.

THE UNDERSIGNED represent and agree with said ASSIGNEE, its successors and assigns, that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the UNDERSIGNED, and that full right to convey the same as herein expressed is possessed by the UNDERSIGNED.

IN TESTIMONY WHEREOF, THE UNDERSIGNED have hereunto set their hand on the dates indicated below.

Signature MATOBA, Yoshiki	July 5, 2016
H 되는 하는 기 기 기 기 기 기 기 기 기 기 기 기 기 기 기 기 기 기	July 5, 2016 Date
Skingo Suleoi Signature TSUBOI, Shingo Date	July 5, 2016
画井俊広 Signature SAKAI, Toshihiro Date	July 5, 2016

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RECORDED: 07/27/2016